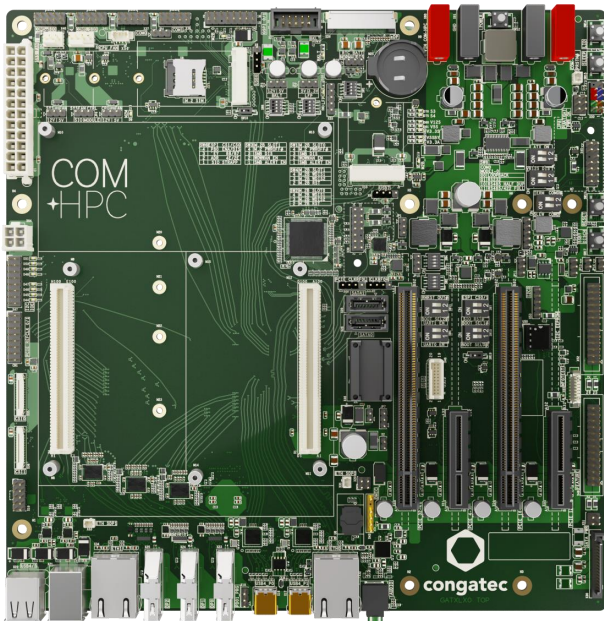


Application Carrier for COM-HPC Client

conga-HPC/uATX

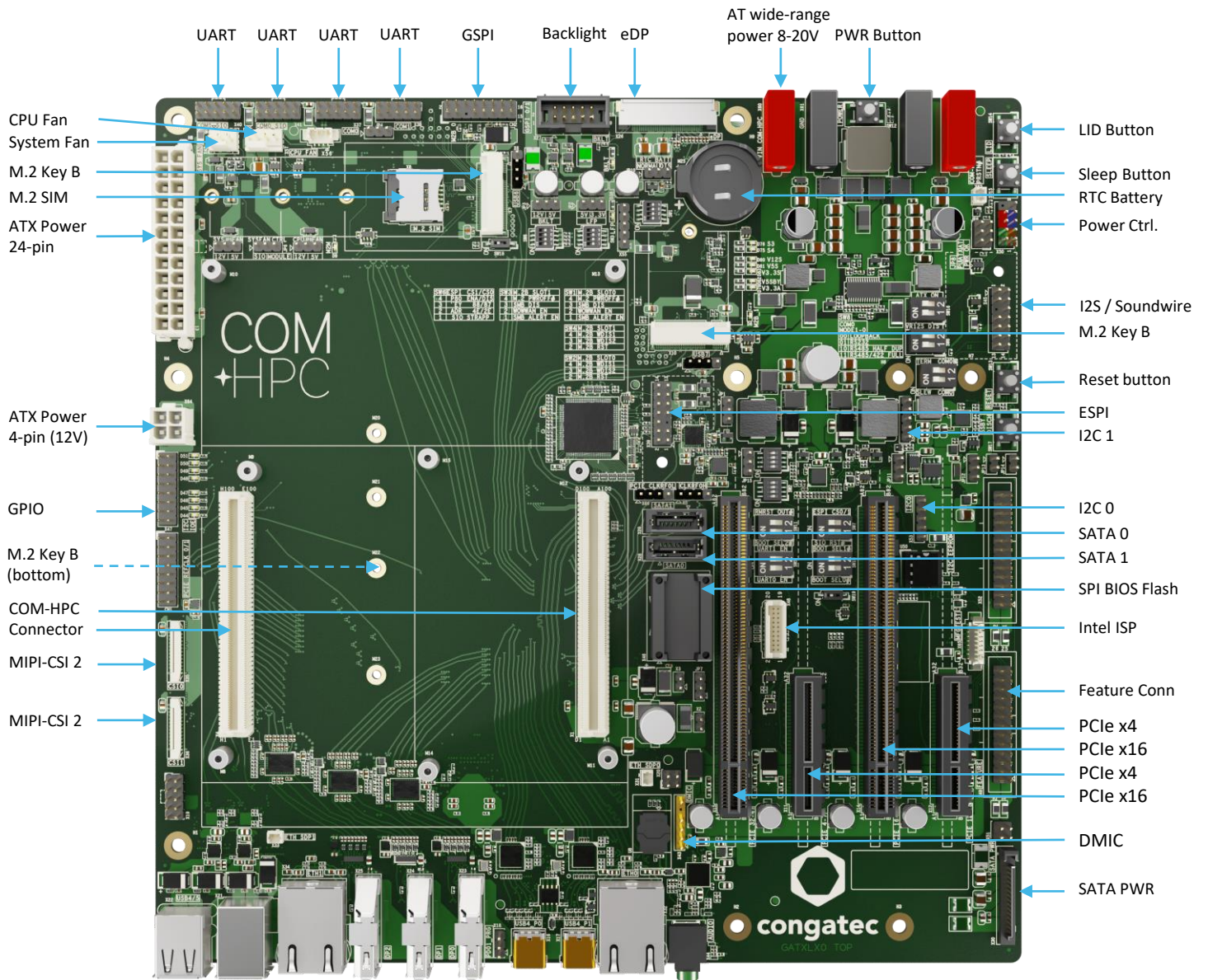


- Application carrier board for COM-HPC
- Scalable μ ATX motherboard
- Longevity by module concept
- Quick start for COM-HPC

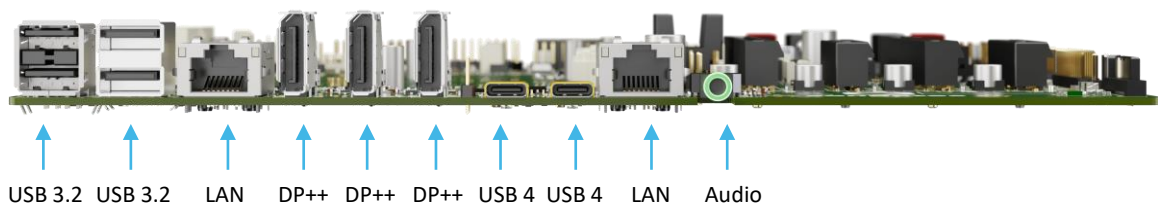
COM+HPC™

Form Factor	Standard Micro-ATX
Board Type	Application Carrier Board for COM-HPC Client Type Modules (Sizes A, B, C)
Internal IO	<p>2x PCIe Gen4 x16 2x PCIe Gen4 x4 2x SATA III 1x 2.5" Disk Drive Power connector 1x M.2 Key B 2242/3042/2260/2280 (USB2, PCIe x2, SIM) 1x M.2 Key B 2230/3030/2242/3042 (USB2, PCIe x2) 1x M.2 Key M 2242/2260/2280/22110 (PCIe x4) 1x eDP (optional for LVDS) 1x DMIC header 1x I2S/SoundWire header 2x MIPI CSI2/3 4-lane camera FFC 2x UART native by module 2x UART by Super IO 1x General Purpose SPI 2x I2C header 1x SMB header 12x GPIO by header 1x Feature header with system control signals 1x System Fan 1x CPU Fan 1x RTC CMOS battery holder 1x Power button 1x Reset button 1x LID button 1x Sleep button 1x SPI boot flash socket 1x Intel ISP header 1x ATX power connector 24-pin 1x AT banana power jacks 8-20V</p>
External IO	<p>1x Dual USB 2 2x Dual USB 3.2 up to 10Gbps 2x USB4 with Thunderbolt Retimer (1x with Power Delivery) 3x DP++ with 8.1 Gbps Re-driver 2x 2.5GbE RJ45 with IEEE1588 support 1x Audio Jack 4-pin on-carrier HDA codec</p>
Power Management	ACPI 6.0
Operating Systems	Microsoft® Windows 10 Microsoft® Windows 10 IoT Enterprise Linux Yocto RTS Hypervisor
Temperature Range	Commercial: Operating Temperature: 0 to +60°C Storage Temperature: -20 to +80°C
Humidity	Operating: 10 to 90% r. H. non cond. Storage: 5 to 95% r. H. non cond.
Size	244 x 244 mm ²

conga-HPC/uATX | Internal IO



conga-HPC/uATX | Front Panel



conga-HPC/uATX | Order Information

Article	PN	Description
conga-HPC/uATX-Client	065620	COM-HPC Client μ ATX carrier board suitable for congatec COM-HPC modules with Size A,B and C.

conga-HPC/uATX | Compatible Modules



[conga-HPC/cALS](#)

COM-HPC Client Size C high performance module based on 12th Gen Intel® Core™ processor series (code name "Alder Lake")



[conga-HPC/cALP](#)

COM-HPC Client Size A high performance module based on 12th Gen Intel® Core™ processor series (code name "Alder Lake")



[conga-HPC/cTLH](#)

COM-HPC Client Size B high performance module based on 11th Gen Intel® Core™ processor series (code name "Tiger Lake-H")



[conga-HPC/cTLU](#)

COM-HPC Client Size A high performance module based on 11th Gen Intel® Core™ processor series (code name "Tiger Lake")